

9014W(BR3DG9014W)

Rev.C Feb.-2015

描述 / Descriptions

SOT-323 塑封封装 NPN 半导体三极管。Silicon NPN transistor in a SOT-323 Plastic Package.

特征 / Features

P_C 大, h_{FE} 高且特性好, 与 9015W(BR3CG9015W) 互补。

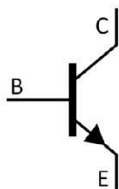
High P_C and h_{FE} , excellent h_{FE} linearity, complementary pair with 9015W(BR3CG9015W).

用途 / Applications

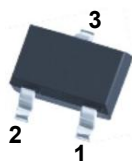
用于低电平、低噪声的前置放大器。

Low frequency, low noise pre-amplifier.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN1 : Emitter

PIN 2 : Base

PIN 3 : Collector

印章代码 / Marking

h_{FE} Classifications Symbol	A	B	C	D
h_{FE} Range	60~150	100~300	200~600	400~1000
Marking	HJ6A	HJ6B	HJ6C	HJ6D

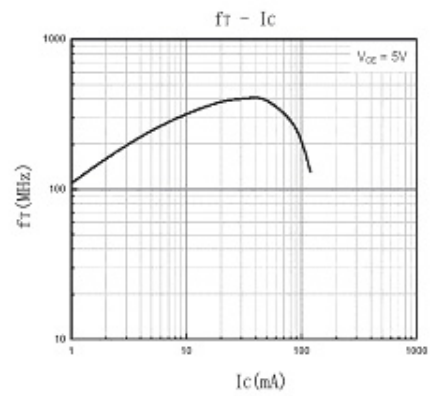
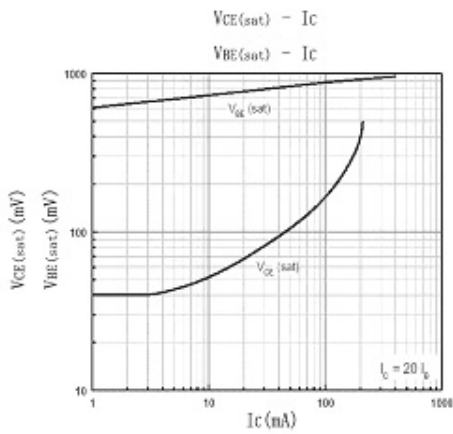
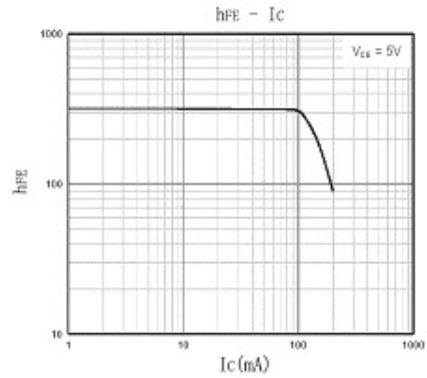
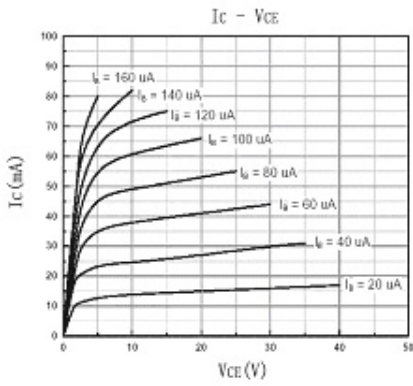
极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Collector to Base Voltage	V_{CBO}	50	V
Collector to Emitter Voltage	V_{CEO}	45	V
Emitter to Base Voltage	V_{EBO}	5.0	V
Collector Current - Continuous	I_C	100	mA
Collector Power Dissipation	P_C	250	mW
Junction Temperature	T_j	150	°C
Storage Temperature Range	T_{stg}	-55~150	°C

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Collector to Base Breakdown Voltage	V_{CBO}	$I_C=0.1mA$ $I_E=0$	50			V
Collector to Emitter Breakdown Voltage	V_{CEO}	$I_C=1.0mA$ $I_B=0$	45			V
Emitter to Base Breakdown Voltage	V_{EBO}	$I_E=0.1mA$ $I_C=0$	5.0			V
Collector Cut-Off Current	I_{CBO}	$V_{CB}=50V$ $I_E=0$			0.05	μA
Emitter Base Cut-Off Current	I_{EBO}	$V_{EB}=5.0V$ $I_C=0$			0.05	μA
DC Current Gain	h_{FE}	$V_{CE}=5.0V$ $I_C=1.0mA$	60		1000	
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=100mA$ $I_B=5.0mA$		0.14	0.3	V
Base-Emitter Saturation Voltage	$V_{BE(sat)}$	$I_C=100mA$ $I_B=5.0mA$		0.84	1.0	V
Collector-Emitter Voltage	V_{BE}	$V_{CE}=5.0V$ $I_C=2.0mA$		0.63	0.7	V
Transition Frequency	f_T	$V_{CE}=5.0V$ $I_C=10mA$	150	270		MHz
Output Capacitance	C_{ob}	$V_{CB}=10V$ $I_E=0$ $f=1.0MHz$		2.2	3.5	pF

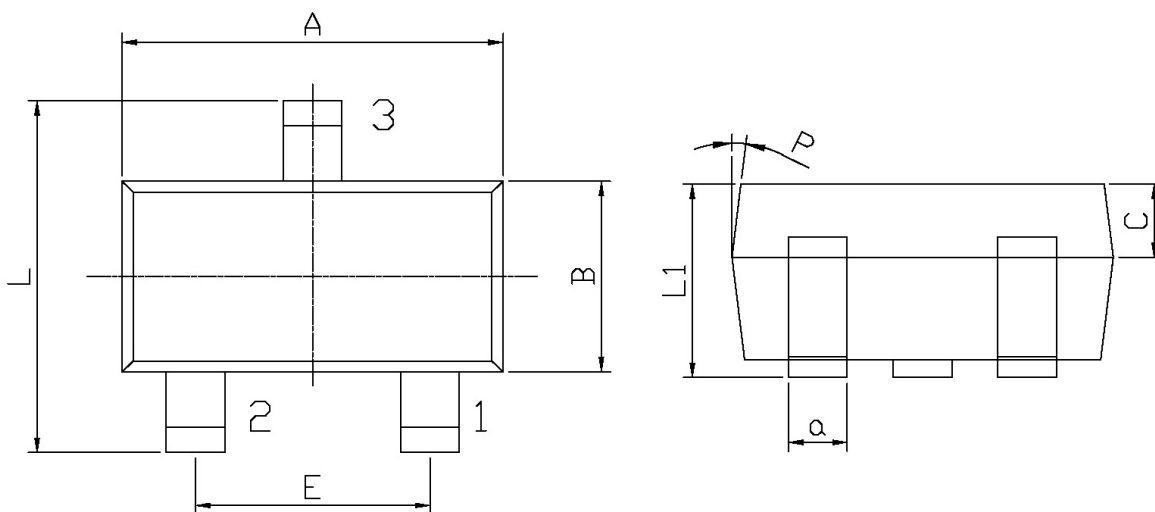
电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

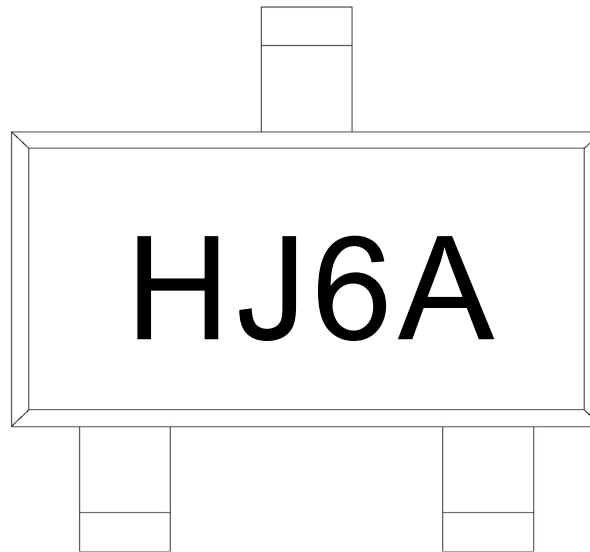
SOT-323

单位: mm



Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	1.95	2.35	C	0.30	0.50
L	2.00	2.2	L1	0.85	1.15
E	1.20	1.40	a	0.20	0.40
B	1.15	1.35	P	7°	

印章说明 / Marking Instructions



说明：

H： 为公司代码

J6： 为型号代码

A： 为 h_{FE} 分档代码

Note:

H: Company Code.

J6: Product Type.

A : h_{FE} Classifications Symbol

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 $25 \sim 150^\circ\text{C}$ ，时间 $60 \sim 90\text{sec}$;
- 2、峰值温度 $245 \pm 5^\circ\text{C}$ ，时间持续为 $5 \pm 0.5\text{sec}$;
- 3、焊接制程冷却速度为 $2 \sim 10^\circ\text{C}/\text{sec}$.

Note:

- 1.Preheating: $25 \sim 150^\circ\text{C}$, Time: $60 \sim 90\text{sec}$.
- 2.Peak Temp.: $245 \pm 5^\circ\text{C}$, Duration: $5 \pm 0.5\text{sec}$.
3. Cooling Speed: $2 \sim 10^\circ\text{C}/\text{sec}$.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度： $270 \pm 5^\circ\text{C}$

时间： 10 ± 1 sec.

Temp.: $270 \pm 5^\circ\text{C}$

Time: 10 ± 1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/盒	Reel	Inner Box 盒	Outer Box 箱
SOT-323	3,000	10	30,000	8	240,000	7" × 8	180×120×180	385×257×392

使用说明 / Notices